

TITLE

Modified Polyacetals for Plating

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ABSTRACT OF THE DISCLOSURE

10 A polyacetal mixture for processing into a polyacetal article to be acid-etched and plated comprises a polyacetal resin blend comprising 97 – 99.9wt% polyacetal and 0.1 – 3wt% of semicrystalline or amorphous thermoplastic non-polyacetal resin of molecular weight 5,000 – 50,000; and acid-soluble particles such as calcium carbonate. The acid-soluble particles are present in an amount from 2 to 6% by weight of the polyacetal blend, at least 98% of said acid-soluble particles being in the size range preferably from 0.1 to 2 micrometers. The mixture preferably also comprises acid-insoluble
15 inorganic particles in particular fumed silica, present in an amount from 1/5 to 1/50 the weight of the acid-soluble particles, the size of the acid-insoluble particles being from 1/20 to 1/100 the size of the acid-soluble particles. The plated polyacetal articles have superior aesthetic appearance while retaining good plating adhesion and good resistance of the polyacetal to chemical
20 attack.